

CXA3222N

TX Gain Control Amplifier

Description

CXA3222N is a TX gain control amplifier suitable for CDMA cellular/PCS phone.

Features

- Wide gain control range
- Linear gain slope
- Wideband operation (50MHz to 300MHz)
- Very small package (8 Pin SSOP)
- Low voltage operation
- High output IP3
- Power save function included

Absolute Maximum Ratings

 Supply voltage 	Vcc	6	V
 Operating temperature 	Topr	-55 to +125	°C
 Storage temperature 	Tstg	-65 to +150	°C
		0.01.0	

- Supply voltage range -0.3 to 6 V
- Logic input voltage -0.3 to Vcc + 0.3 V
 Signal input voltage -0.3 to Vcc + 0.3 V
- Signal input voltage -0.3 to Vcc + 0.3 V
 Differental signal input voltage 0 to 2.5 V

Operating Condition

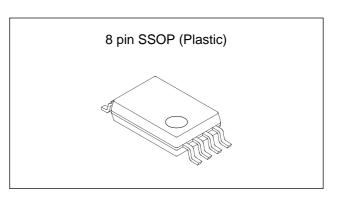
Supply voltage	Vcc	2.7 to 3.8	V

Applications

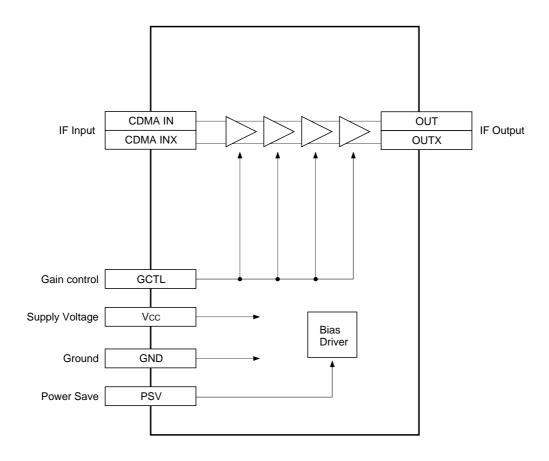
CDMA cellular/PCS phone

Structure

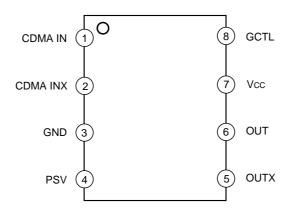
Bipolar silicon monolithic IC



Block Diagram



Pin Configuration



Pin Description

Pin No.	Symbol	Pin voltage TYP (V)	Equivalent circuit	Description
1	CDMA IN	1.1	40k 40k	Differential input pins for CDMA
2	CDMA INX	1.1		transmit IF signal.
3	GND	0		Ground.
4	PSV		4 4 4 4 4 4 4 4 4 4 4 4 4 4	Power save function pin. High: Active Low: Power save
5	ουτχ	_	5 6 Vcc2 510 510 510 Vcc2 12.25k 12.25k	Differential output pins for transmit IF signal.
6	OUT	_		Open collector output.
7	Vcc	3.0		Positive power supply.
8	GCTL		Vcc1	Gain control pin.

Electrical Characteristics

DC Characteristics

(Vcc = 3.0V, Ta = 27°C)

			(,	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Current consumption 1	lcc1	Vpsv = 3.0V, Vgctl = 1.5V, Pin 7	10	15.7	21.5	mA
Current consumption 2	Icc2	Vpsv = 0 V, Vgctl = 1.5V, Pin 7	5	18	40	
Input current pin 4H	IpsvH	Vpsv = 3.0V			1	
Input current pin 4L	lpsvL	Vpsv = 0 V	-15			μA
Input current pin 8H	IgctlH	Vgctl = 3.0V			1	
Input current pin 8L	IgctIL	Vgctl = 0.5V	-1			
PSV high voltage	VpsH	Pin 4	2.5			v
PSV low voltage	VpsL	Pin 4			0.5	

AC Characteristics

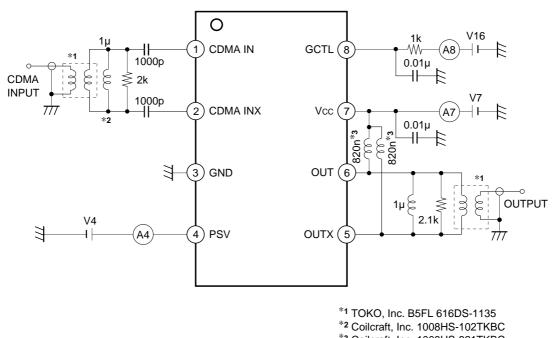
(Vcc = 3.0V, Ta = 27°C)

			(*00	- 0.0 (/, iu =	21 0)
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Operating frequency range	Fr		50		300	MHz
Gain 2.3	G2.3	f = 130.38MHz, level = -22.5dBm, Vgctl = 2.3V	13	17	21	
Gain 1.5	G1.5	Vgctl = 1.5V	-28	-24	-20	dB
Gain 1.0	G1.0	Vgctl = 1.0V	-58	-54	-50	
Gain 0.7	G0.7	Vgctl = 0.7V	-75	-70	-65	
Gain slope	GCLIN	Gain at Vgctl = 2.0V – Gain at Vgctl = 1.0V	56	59	62	dB/V
Input level 3rd order intercept point	IIP3	G = 15dB ^{*1} f1 = 129.38MHz, f2 = 131.38MHz Measure of 130.38MHz	-8.5	-4.5		dBm
Noise Figure	NF	G = 15dB ^{*1} Measure of 130.38MHz		28	32	dB

*1 Adjust GCTL voltage, and set the overall gain to 15dB.

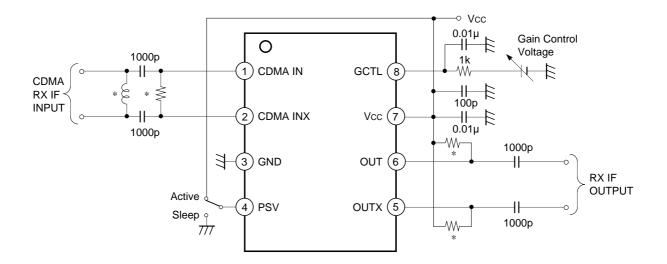
CXA3222N

Measurement Circuit



*3 Coilcraft, Inc. 1008HS-821TKBC

Application Circuit



* Must be adjusting values to result a best impedance matching between BPF filter and this IC.

Application circuits shown are typical examples illustrating the operation of the devices. Sony cannot assume responsibility for any problems arising out of the use of these circuits or for any infringement of third party patent and other right due to same.

Design Reference Values

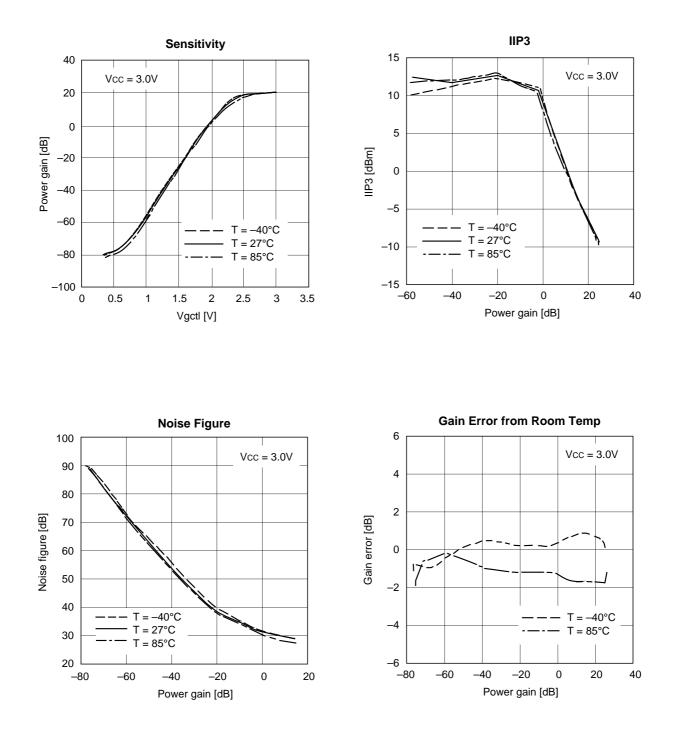
Single ended measurement

(Vcc = 3.0V, Ta = 27°C)

Item	Symbol	Conditions	Тур.	Unit
Input resistance	Rin		10	kΩ
Input capacitance	Cin	f _ 120 29MUz \/actl _ 1 5\/	0.92	pF
Output resistance	Rout	f = 130.38MHz, Vgctl = 1.5V	6	kΩ
Output capacitance	Cout		0.9	pF

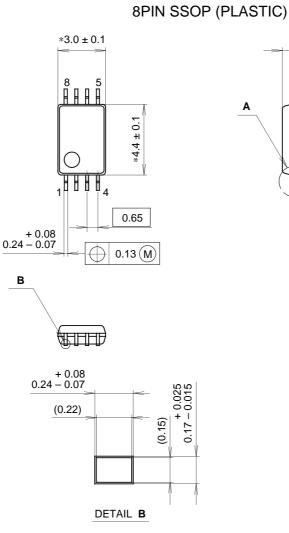
Notes on Operation

- 1) This IC is a wideband amplifier with wide gain control range. The decouping capacitors between GND Pin and Vcc Pin should be as close to the IC as possible.
- 2) The resistors connected to Pins 5 and 6 should be as close to the IC as possible.
- 3) This IC assumes the excellent characteristics when the differential input impedance between Pins 1 and 2 is 500Ω. Refer to the Measurement Circuit for the external element settings, etc.
- 4) Pay attention to handling this IC because its electrostatic discharge strength is weak.



Package Outline

Unit: mm



NOTE: Dimension "*" does not include mold protrusion.

SONY CODE	SSOP-8P-L01
EIAJ CODE	SSOP008-P-0044
JEDEC CODE	

PACKAGE STRUCTURE

PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER / PALLADIUM PLATING
LEAD MATERIAL	COPPER ALLOY
PACKAGE MASS	0.04g

+ 0.2 1.25 – 0.1

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 6.4 ± 0.2

0.25

0.1 ± 0.05

0° to 10°

0.1

 0.6 ± 0.15

(0.5)

DETAIL A